8-bit Proprietary Microcontrollers

CMOS

F²MC-8L MB89051 Series

MB89F051/MB89051

■ DESCRIPTION

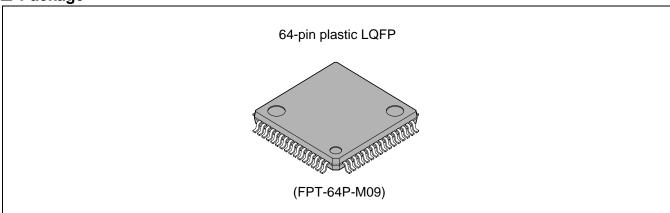
The MB89051 series is a general-purpose, single-chip microcontroller that features a compact instruction set and contains a range of peripheral function set and timers, serial interface, a PWM timer, the USB hub function and the USB function. The USB hub function, in particular, supports five down ports (one of them is dedicated to an internal function) allowing them to interface with other USB devices. The microcontrollers also contain one USB function channel to support full speed.

■ FEATURES

- Package type
 64-pin LQFP Package (0.65 mm pitch)
- High-speed operations at low voltage
 Minimum execution time: 0.33 μs (Automatically generates a 12 MHz main clock and a 48 MHz USB interface
 synchronization clock with an externally supplied 6 MHz clock and the internal PLL circuit.)

(Continued)

■ Package





• F2MC-8L CPU core

Instruction set that is optimum to the controllers

- -Multiplication and division instructions
- -16-bit arithmetic operations
- -branch instructions by bit testing
- -bit manipulation instructions, etc.
- PLL clock control

The internal PLL clock circuit allows the use of low-speed clocks which are advantageous to noise characteristics.

(6 MHz externally-supplied clock→12 MHz internal system clock)

· Various timers

8-bit PWM timer (can be used as either 8-bit PWM timer 2 channels or PPG timer 1 channel)

Internal 21-bit timebase timer

- Internal USB transceiver circuit (Compatible with full and low speeds)
- USB hub

USB function Compliant to USB Protocol Revision 1.0

Five downstream port channels (One of these channels is dedicated to a function.)

Automatically responds to all USB protocols by hardware.

Descriptor configuration is provided as ROM data for automatic responding by hardware (Vender ID and product ID).

String data is not supported.

Allows switching between BUS power supply and own power supply mode.

Power supply to the USB down port is controlled port by port.

USB function

USB function Compliant to USB Protocol Revision 1.0

Support for full speed when using hub

Support for both low and full speeds when using function

Allows four endpoints to be specified at maximum.

Types of transfer supported: control/interrupt/bulk/isochronous

Built-in DMAC (Maps the buffer for each endpoint on to the internal RAM to directly access the memory for function's send and receive data.)

• UART/SIO, SIO Serial Interface

Built-in UART/SIO function (selectable by switching) × 1 channel

Built-in SIO (3.3 V) × 2 channels

I²C interface*1

Supports Philips I²C bus standards

Uses a two-wire data transfer protocol

Master/slave send/receive

External interrupt

External interrupt (level detection × 7 channels)

Seven inputs are independent of one another and can also be used for resetting from low-power consumption mode (the L-level detection feature available) .

Clock output functions

Able for 12 MHz*2 and 6 MHz*2 clocks to output. (dedicated pins, 3 V)

• Low power consumption (standby mode supported)

Stop mode (There is almost no current consumption since oscillation stops.)

Sleep mode (This mode stops the running CPU.)

(Continued)

A maximum of 41 general-purpose I/O ports

General-purpose I/O ports (CMOS): 37 (7 of 3 V ports)

General-purpose I/O ports (Nch open drain): 4

Power supply

Supply voltage: 3.3 V \pm 0.3 V or 5.0 V \pm 0.5 V

· Operating temperature

 $T_A = -40$ ° to +85 °C (When the USB function is not in use.)

 $T_A = 0$ °C to +70 °C (When the USB function is in use.)

*1: I2C license

The customer is licensed to use Philips I²C patent when using this product in an I²C system that complies with the Philips I²C standard specifications.

*2: When an external supply clock is at 6 MHz.

■ PRODUCT LINEUP

	Part r	number	MD00054	MD90E0E4			
Parameter			MB89051	MB89F051			
ROM size			32 KB	32 KB (FLASH)			
RA	M size		2	2 KB			
Pa	ckage		LQFP-64 (I	FPT-64P-M09)			
Oth	ners		MASK product	FLASH product/EVA product			
СР	'U functio	ons	Number of instructions : 136 nstruction bit length : 8 bits nstruction length : 1 to 3 bytes Data bit length : 1, 8, and 16 bits Minimum execution time : 0.33 µs (6 MHz) nterrupt processing time : 3 µs (6 MHz)				
	Genera purpose		General purpose I/O ports (37 : CMOS (7 of 3 V ports) , 4 : Nch open drain)				
	USB hub		Upstream port : 1 channel Downstream port : 5 channels (One is dedicated to an internal function.) Port power supply control method : By individual port Allows selection between own power supply and bus power supply				
Peripheral functions	USB fur	nction	Supports full speed: when using hub Supports full and low speeds: when using function End point max 4 Built-in DMAC (Can be set to DMA transfer to the internal RAM)				
eral	PWM tii	mer	8-bit PWM timer operation 2 channels (can also be used as a PPG 1 channel timer)				
Periph	UART	JART SIO Allows switching between UART (clock-synchronous/asynchronous data transfer allow and SIO (simple serial transfer).		chronous/asynchronous data transfer allowed)			
	SIO	•	SIO (simple serial) × 2 channels (3 V)				
	I ² C interface		One channel. Supports Phillips I ² C bus standards. Uses a 2-wire protocol for communications with other devices.				
	Timeba timer	se	21-bit timebase timer				
	Clock o	utput	Allows clock output of 12 MHz* and 6 MHz*	(3 V)			
Sta	andby mo	ode	Sleep mode and Stop mode				

^{*:} When external supply clock is at 6 MHz.

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

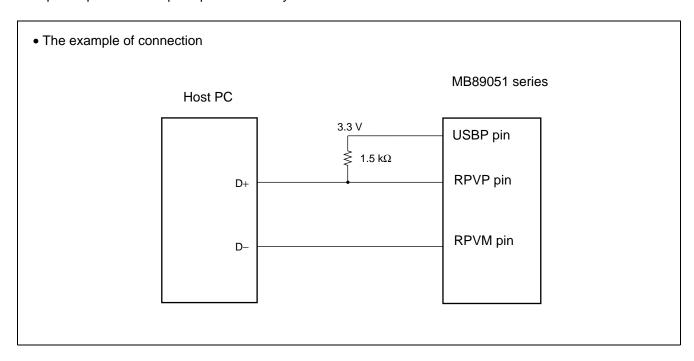
• Before evaluating using the FLASH product, it is necessary to confirm its differences from the product that will actually be used.

2. Current Consumption

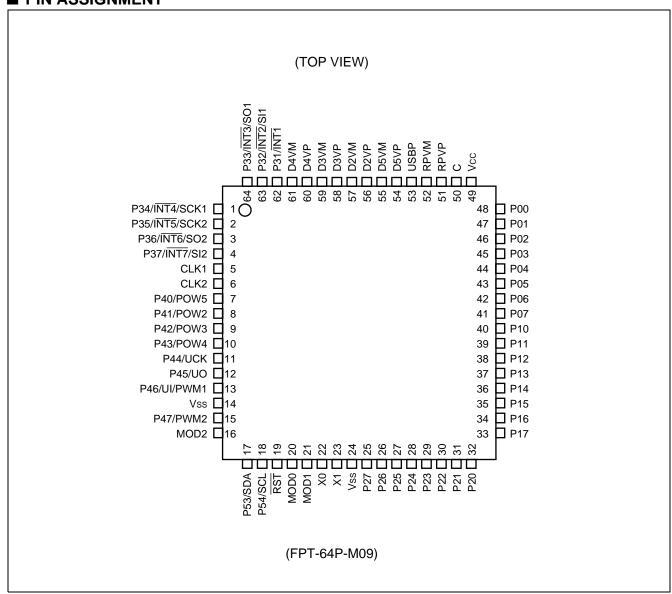
- When operating at low speed, FLASH products will consume more current than mask ROM products. However, in sleep/stop mode the current consumption is the same.
- For detailed information on each package, see "■PACKAGE DIMENSIONS"

3. USB Pull-up Resistor control

• Remains in high impedance state until USB connection take place. Before the USB connection, use USBP pin output to control pull-up resistance by software.



■ PIN ASSIGNMENT



■ PIN DESCRIPTION

Pin No.	Pin name	Circuit type	Function
1	P34/INT4/ SCK1	E	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO1 clock I/O
2	P35/INT5/ SCK2	Е	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 clock I/O
3	P36/INT6/ SO2	В	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 serial data output
4	P37/ĪNT7/SI2	E	General-purpose CMOS I/O pin The external interrupt input is a hysteresis input. (Level detection) SIO2 serial data input
5	CLK1	М	6 MHz clock output pin (When external supply clock is at 6 MHz.)
6	CLK2	М	12 MHz clock output pin (When external supply clock is at 6 MHz.)
7	P40/POW5	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
8	P41/POW2	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
9	P42/POW3	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
10	P43/POW4	В	General-purpose CMOS I/O pin This pin also serves as USB Down Port power control signal.
11	P44/UCK	Е	General-purpose CMOS I/O pin UART/S10 clock I/O
12	P45/UO	В	General-purpose CMOS I/O pin UART/S10 serial data output
13	P46/UI/ PWM1	N	Nch open drain general-purpose I/O pin UART/S10 serial data input PWM timer
14	Vss	_	Power supply pin (GND)
15	P47/PWM2	К	Nch open drain general-purpose I/O pin PWM timer
16	MOD2	F	An operating mode designation pin. Connect directly to Vss.
17	P53/SDA	К	Nch open drain general-purpose I/O pin Also serve as I ² C interface data input/output pin.
18	P54/SCL	К	Nch open drain general-purpose I/O pin Also serve as I ² C interface clock input/output pin.
19	RST	I	Reset pin (Reset on the negative logic low level.)
20	MOD0	F	An operating mode designation pin. Connect directly to Vss.
21	MOD1	F	An operating mode designation pin. Connect directly to Vss.

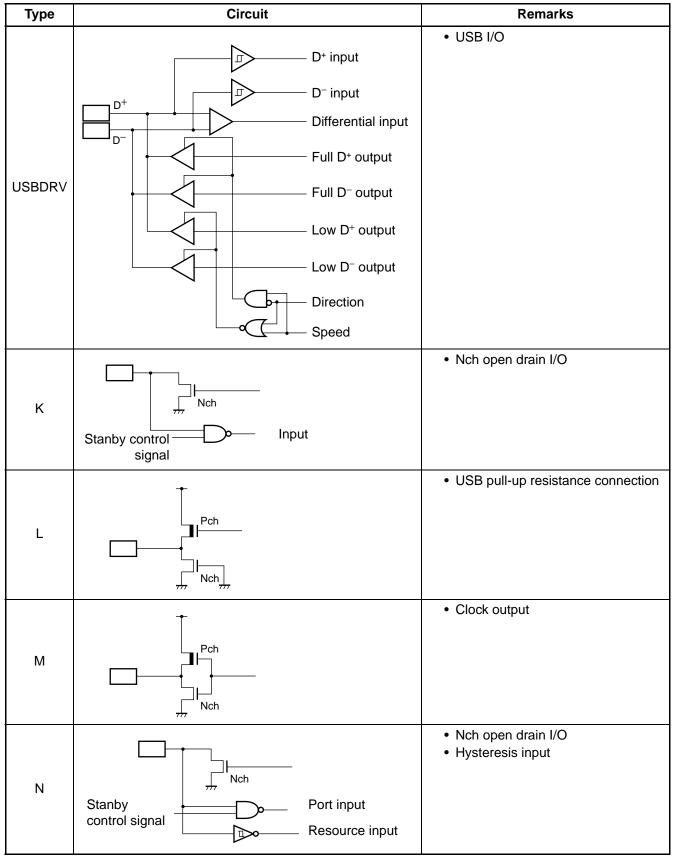
Pin No.	Pin name	Circuit type	Function
22	Х0	А	Ding for the connection of crystal application circuit (6 MHz)
23	X1		Pins for the connection of crystal oscillation circuit.(6 MHz)
24	Vss	_	Power supply pin (GND)
25	P27	В	General-purpose CMOS I/O pin*
26	P26	В	General-purpose CMOS I/O pin*
27	P25	В	General-purpose CMOS I/O pin*
28	P24	В	General-purpose CMOS I/O pin*
29	P23	В	General-purpose CMOS I/O pin*
30	P22	В	General-purpose CMOS I/O pin*
31	P21	В	General-purpose CMOS I/O pin*
32	P20	В	General-purpose CMOS I/O pin*
33	P17	В	General-purpose CMOS I/O pin
34	P16	В	General-purpose CMOS I/O pin
35	P15	В	General-purpose CMOS I/O pin
36	P14	В	General-purpose CMOS I/O pin
37	P13	В	General-purpose CMOS I/O pin
38	P12	В	General-purpose CMOS I/O pin
39	P11	В	General-purpose CMOS I/O pin
40	P10	В	General-purpose CMOS I/O pin
41	P07	В	General-purpose CMOS I/O pin
42	P06	В	General-purpose CMOS I/O pin
43	P05	В	General-purpose CMOS I/O pin
44	P04	В	General-purpose CMOS I/O pin
45	P03	В	General-purpose CMOS I/O pin
46	P02	В	General-purpose CMOS I/O pin
47	P01	В	General-purpose CMOS I/O pin
48	P00	В	General-purpose CMOS I/O pin
49	Vcc	_	Power supply pin.
50	С	_	Connect an external capacitor of 0.1 μ F. When using with 3.3 V power supply, connect this pin with the Vcc pin to set to 3.3 V input.
51	RPVP	USBDRV	USB route port + pin
52	RPVM	USBDRV	USB router port – pin
53	USBP	L	USB pull-up resistance connection pin.
54	D5VP	USBDRV	USB down port 5 + pin
55	D5VM	USBDRV	USB down port 5 – pin

^{*:} For output only on the emulator.

Pin No.	Pin name	Circuit type	Function
56	D2VP	USBDRV	USB down port 2 + pin
57	D2VM	USBDRV	USB down port 2 – pin
58	D3VP	USBDRV	USB down port 3 + pin
59	D3VM	USBDRV	USB down port 3 – pin
60	D4VP	USBDRV	USB down port 4 + pin
61	D4VM	USBDRV	USB down port 4 – pin
62	P31/INT1	В	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection))
63	P32/INT2/SI1	E	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection)) SIO1 serial data input
64	P33/INT3/ SO1	В	General-purpose CMOS I/O pin External interrupt input (Hysteresis input (level detection)) SIO1 serial data output

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
А	X1 X0 X0 Stanby control signal	 Oscillation feedback resistance : 1 MΩ approx.
В	Pullup control register Stanby control Input signal	• CMOS I/O
E	Pullup control register Pullup control register Port input control signal Resource input	CMOS I/O Hysteresis input
F	Input	CMOS input
I	Pch Nch Input	Hysteresis I/O Pullup resistance



■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input or output pins other than the medium- and high-voltage pins or if voltage higher than the rating is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also take care to prevent the analog input from exceeding the digital power supply (Vcc) when the power supply to the analog power system is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions and latchup leading to permanent damage to the pins. These unused pins should be connected to a pullup or pulldown resistance of at least 2 k Ω between the pin and the power supply.

Unused I/O pins should be placed in output state to leave it open or pins that are in input state should be handled the same as unused input pins.

3. Note to noise in the External Reset Pin (RST)

If the reset pulse applied to the external reset pin (\overline{RST}) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (\overline{RST}) .

4. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

5. Note on the clock during operation

This microcontroller uses a PLL for generating the main clock signal. If the oscillator is removed or the clock input stops during operation, therefor, the microcontroller may keep on operating at the free-running frequency of the self-oscillation circuit in the PLL. The operation is not however guaranteed.

6. About port 2 (P20 to P27)

Port 2 serves as an output-only terminal on the emulator.

■ PROGRAMMING AND ERASING FLSH MEMORY

1. Flash Memory

The flash memory is located between 8000_H and FFFF_H in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as mark ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the CPU, providing an efficient method of updating program and data.

2. Flash Memory Features

- 32 Kbyte × 8-bit configuration (16 K + 8 K + 8 K sectors)
- Automatic programming algorithm (Embedded Algorithm* : Equivalent to MBM29LV200)
- Includes an erase pause and restart function
- Data polling and toggle bit for detection of program/erase completion
- Detection of program/erase completion via CPU interrupt
- Compatible with JEDEC-standard command
- Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles: 10,000 (Min)

3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

4. Flash Memory Register

Control status register (FMCS)

Address	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Initial value
002Ен	INTE	RDYINT	WE	RDY	Re- served	Re- served	_	Re- served	000Х00Х0в
	R/W	R/W	R/W	R	R/W	R/W	_	R/W	

5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector for both during CPU access and a flash memory programming.

Sector configuration of flash memory

Flash Memory	CPU Address	Programmer Address*
16 Kbytes	FFFF _H to C000 _H	1FFFFн to 1С000н
8 Kbytes	BFFF _H to A000 _H	1BFFFн to 1A000н
8 Kbytes	9FFFн to 8000н	19FFFн to 18000н

^{*:} Programmer address

The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general-purpose parallel programmer.

^{*:} Embedded Algorithm is a trademark of Advanced Micro Devices.

6. ROM Programmer Adaptor and Recommended ROM Programmers

Package	Compatible adapter	Compatible programmers and models
Fackage	Sunhayato Corp.	Ando Denki K.K.
FPT-64P-M09	FLASH-64QF2-32DP-8LF3	AF9708 (ver 1.60 or higher) AF9709 (ver 1.60 or higher)

• Inquiry:

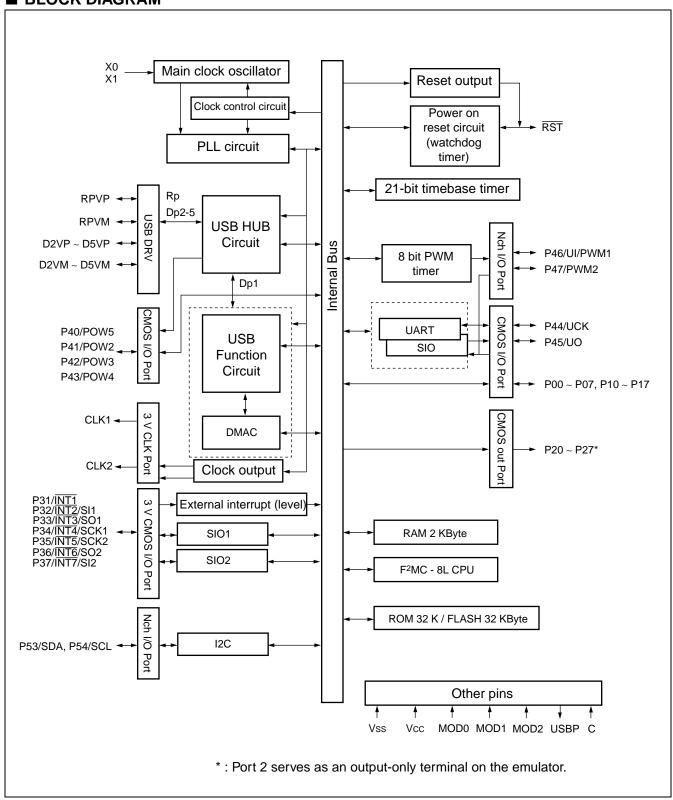
Sunhayato Corp. : TEL : 81-3-3984-7791

FAX: 81-3-3971-0535

E-mail: adapter@sunhayato.co.jp

Ando Denki K. K. : TEL : 81-3-3733-1160

■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Size

The MB89051 microcontroller offers a memory space of 64 Kbytes consisting of the I/O, RAM and ROM areas. The memory space contains areas that are used for specific purposes, such as a general-purpose register and a vector table.

• I/O area (addresses: 0000H through 007FH)

This area is assigned with the control and data registers, for example, of peripheral functions to be built in. The I/O area is as accessible as the memory since the area is assigned to a part of the memory space. Direct addressing also allows the area to be accessed faster.

RAM area

As an internal data area, a static RAM is built in.

The internal RAM capacity varies with the product type.

The area 80H to FFH can be accessed at high speed with direct addressing.

The area 100H to 1FFH can be used a general-purpose register area. (The usable area is limited depending on the product.)

When reset, RAM data becomes undefined.

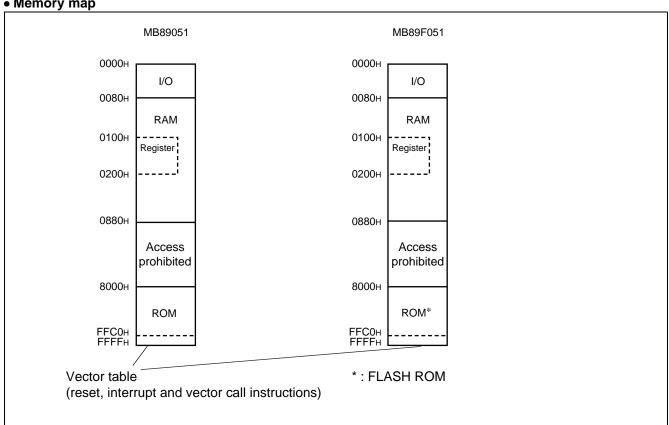
ROM area

As an internal program area, a ROM is built in.

The internal RAM capacity varies with the product type.

The area FFC0_H to FFFF_H should be used for a vector table, for example.

Memory map



2. Registers

The MB89051 series has two types of registers; the registers dedicated to specific purposes in the CPU and the general-purpose registers.

The dedicated registers are as follows:

Program counter (PC) : A 16-bit register to indicate locations where instructions are stored.

Accumulator (A)

A 16-bit register for temporary storage of operations. In the case of an 8-bit

data processing instruction, the lower one byte is used.

Temporary accumulator (T)

A 16-bit register which performs operations with the accumulator. In the case of

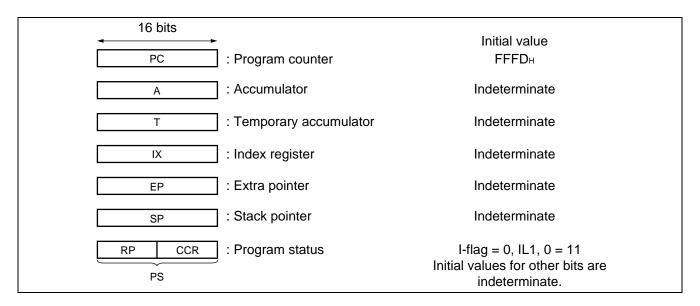
an 8-bit data processing instruction, the lower one byte is used.

Index register (IX) : A 16-bit register for index modification.

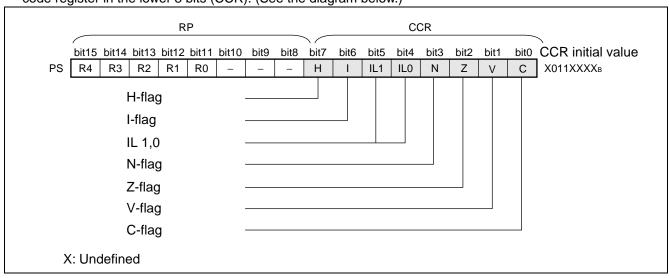
Extra pointer (EP) : A 16-bit register to point to a memory address.

Stack pointer (SP) : A 16-bit register to indicate a stack area.

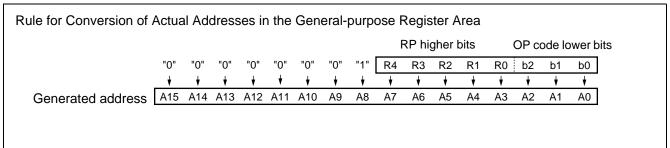
Program status (PS) : A 16-bit register to store a register pointer or a condition code.



The PS register can further be divided into the register bank pointer in the higher 8 bits (RP) and the condition code register in the lower 8 bits (CCR). (See the diagram below.)



The RP points to the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule shown next.



The CCR consists of the bits indicating arithmetic operation results or transfer data contents and the bits that control CPU operations at the time of an interrupt.

H flag : The flag is set to "1" when an arithmetic operation results in a carry from bit 3 to bit 4 or in a borrow

from bit 4 to bit 3. The bit is cleared to "0" in other instances. The flag is for decimal adjustment

instructions; do not use for other than additions and subtractions.

: Interrupt is enabled when this flag is set to "1." Interrupt is disabled when this flag is set to "0." The I flag

flag is set to "0" when reset.

IL1, 0 Indicates the level of the interrupt currently enabled. An interrupt is processed only if its level is

higher than the value this bit indicates.

IL1	IL0	Interrupt level	High-low		
0	0	1	Higher		
0	1	1	†		
1	0	2	↓		
1	1	3	Lower = no interruption		

: The flag is set to "1" when an arithmetic operation results in setting of the MSB to "1" or is cleared N flag to "0" when the MSB is set to "1."

: The flag is set to "1" when an arithmetic operation results in "0" or is set to "0" in other instances. Z flag

V flag : The flag is set to "1" when an arithmetic operation results in two's complement overflow or is

cleared to "0" if no overflow occurs.

C flag : The flag is set to "1" when an arithmetic operation results in a carry from bit 7 or in a borrow to bit 7. The flag is cleared to "0" if neither of them occurs. In the case of a shift instruction, the flag is

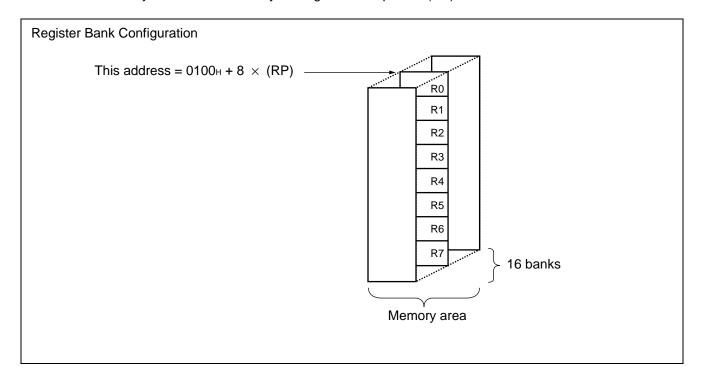
set to the shift-out value.

The following general-purpose registers are provided:

•General-purpose registers : 8-bit data storage registers

The general-purpose registers are 8 bits in length and located in the register banks in the memory. One bank contains eight registers and the MB89051 microcontrollers allow a total of 16 banks to be used at maximum.

The bank currently in use is indicated by the register bank pointer (RP).



■ I/O MAP

Address	Register name	Register description	Read/write	Initial value
00н	PDR0	Port 0 data register	R/W	XXXXXXXX
01н	DDR0	Port 0 direction register	W	00000000
02н	PDR1	Port 1 data register	R/W	XXXXXXXX
03н	DDR1	Port 1 direction register	W	00000000
04н	PDR2	Port 2 data register	R/W	00000000
05н		Reserved area	- 1	1
06н	DDR2	Port 2 direction register	R/W	00000000
07н	SYCC	System clock control register	R/W	XXX11X00
08н	STBC	Standby control register	R/W	0 0 0 1 XXXX
09н	WDTC	Watchdog timer control register	R/W	XXXXXXXX
ОАн	TBTC	Timebase timer control register	R/W	0 0 XXX 0 0 0
0Вн		Vacancy	1	1
0Сн	PDR3/USBP	Port 3 data register/Pull-up register for USB	R/W	XXXXXXXX
0Dн	DDR3/USBPC	Port 3 data direction register/ Pull-up control register for USB	R/W	0000000
0Ен		Reserved area	1	1
0Fн		Vacancy		
10н	PDR4	Port 4 data register	R/W	XXXXXXXX
11н	DDR4	Port 4 direction register	R/W	00000000
12н	PDR5	Port 5 data register	R/W	XXX 1 1 XXX
13н to 15н		Reserved area		
16н to 20н		Vacancy		
21н	PURR0	Port 0 pullup option setting register	R/W	11111111
22н	PURR1	Port 1 pullup option setting register	R/W	11111111
23н	PURR2	Port 2 pullup option setting register	R/W	11111111
24н	PURR3	Port 3 pullup option setting register	R/W	1111111X
25н	PURR4	Port 4 pullup option setting register	R/W	11111111
26н		Reserved area		
27н	CTR1	PWM control register 1	R/W	0000000
28н	CTR2	PWM control register 2	R/W	000X0000
29н	CTR3	PWM control register 3	R/W	X 0 0 0 XXXX
2Ан	CMR1	PWM compare register 1	W	XXXXXXXX
2Вн	CMR2	PWM compare register 2	W	XXXXXXXX
2Сн	CKR	Clock output control register	R/W	XXXXXXX 0 0
2Dн	SCS	Serial clock switching register	R/W	XXXXXXX 0

Address	Register name	Register description	Read/write	Initial value
2Ен	FMCS	Flash memory control status register (Only built-in Flash Memory products)	R, R/W	000X00X0
2Fн	SMC1	Serial mode control register 1	R/W	0000000
30н	SMC2	Serial mode control register 2	R/W	0000000
31н	SSD	Serial status and control register	R	0 0 0 0 1 XXX
32н	SIDR/SODR	Serial input/serial output data register	R/W	XXXXXXXX
33н	SRC	Serial rate control register	R/W	XXXXXXXX
34н	IBSR	I ² C bus status register	R	0000000
35н	IBCR	I ² C bus control register	R/W	00011000
36н	ICCR	I ² C clock regeister	R/W	0 X 0 XXXXX
37н	IADR	I ² C address register	R/W	XXXXXXXX
38н	IDAR	I ² C data register	R/W	XXXXXXXX
39н		Vacancy	1	1
ЗАн	SMR1	Serial mode register 1	R/W	0000000
3Вн	SDR1	Serial data register 1	R/W	XXXXXXXX
3Сн	EIE	External interrupt control register	R/W	00000000
3Dн	EIF	External interrupt flag register	R/W	XXXXXXX 0
3Eн, 3Fн		Vacancy	1	1
40н	HMDR	HUB mode register	R/W	1 0 XXXXX 0
41н	HDSR1	Hub descriptor register 1	R/W	XXXXXXXX
42н	HDSR2	Hub descriptor register 2	R/W	XXXXXXXX
43н	HDSR3	Hub descriptor register 3	R/W	XXXXXXXX
44н	HSTR	Hub status register	R/W	0000000
45н	OCCR	Over current register	R/W	0 XXX 0 0 0 0
46н	DADR	Descriptor ROM address register	R/W	XXXXXXXX
47н		Reserved area	1	1
48н, 49н		Vacancy		
4Ан	SMR2	Serial mode register 2	R/W	0000000
4Вн	SDR2	Serial data register 2	R/W	XXXXXXXX
4Cн, 4Dн		Vacancy	1	1
4Ен	HDSR4	Hub descriptor register 4	R/W	00000101
4Гн		Vacancy	1	1
50н	UMDR	USB reset mode register	R/W	1000XX00
51н	DBAR	DMA base address register	R/W	XXXXXXXX
52н	TDCR0	Transfer data count register 0	R/W	X0000000
53н	TDCR1	Transfer data count register 1	R/W	X0000000
54н		Reserved area		
55н	TDCR21	Transfer data count register 2	R/W	X000000

(Continued)

Address	Register name	Register description	Read/write	Initial value				
56н		Reserved area						
57н	TDCR3	Transfer data count register 3	R/W	X0000000				
58н	UCTR	USB control register	R/W	00000000				
59н	USTR1	USB status register 1	R/W	00000000				
5Ан	USTR2	USB status register 2	R	XXXXXX 0 0				
5Вн	UMSKR	USB interrupt mask register	R/W	0000000				
5Сн	UFRMR1	USB frame status register 1	R	XXXXXXXX				
5 Dн	UFRMR2	USB frame status register 2	R	XXXXXXXX				
5Ен	EPER	USB endpoint enable register	R/W	XXXX 0 0 0 1				
5 F н	EPBR0	End point setup register 0	R/W	X000000				
60н	EPBR11	Endpoint setup register 11	R/W	XX 0 0 0 0 XX				
61н	EPBR12	Endpoint setup register 12	R/W	X0000000				
62н	EPBR21	Endpoint setup register 21	R/W	XX 0 0 0 0 XX				
63н	EPBR22	Endpoint setup register 22	R/W	X0000000				
64н	EPBR31	Endpoint setup register 31	R/W	XX 0 0 0 0 XX				
65н	EPBR32	Endpoint setup register 32	R/W	X0000000				
66н		Reserved area		1				
67н to 78н		Vacancy						
79н		Reserved area						
7Ан		Vacancy						
7Вн	ILR1	Interrupt level setting register 1	W	11111111				
7Сн	ILR2	Interrupt level setting register 2	W	11111111				
7Dн	ILR3	level setting register 3	W	11111111				
7Ен	ILR4	Interrupt level setting register 4	W	11111111				
7F _H		Reserved area	I	1				

• Information about read/write

R/W: Read/write enabled, R: Read only, W: Write only

- · Information about initial values
 - 0: The initial value of this bit is "0".
 - 1: The initial bit of this bit is "1".
 - X: The initial value of this bit is undefined.

Note: Vacancies and reserved spaces are not for use.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(Vss = 0 V)

Parameter	Symbol	Rat	ing	Unit	Remarks
Farameter	Syllibol	Min	Max	Ollit	Remarks
Power supply voltage	Vcc	Vss-0.3	Vss+6.0	V	
		Vss-0.3	Vcc+0.3	V	Other than P31 to P37, P46, P47, P53, P54*1
Input voltage	Vı	Vss-0.3	3.3	V	P31 to P37
		Vss-0.3	Vss+6.0	V	P46,P47,P53, P54*1
		Vss-0.3	Vcc+0.3	V	Other than P31 to P37, P46, P47, P53, P54, CLK1, CLK2, USBP
Output voltage	Vo	Vss-0.3	3.6	V	P31 to P37, CLK1, CLK2, USBP
		Vss-0.3	Vss+6.0	V	P46, P47, P53, 54
Maximum clamp current	I CLAMP	-2.0	2.0	mA	*5
Total maximum clamp cuurent	$\Sigma I_{CLAMP} $		20	mA	*5
"L" level maximum output current	Ю	_	15	mA	Normal output*2
"L" level average output current	lolav	_	4	mA	Normal output*3
"L" level total maximum output current	Σ loL	_	100	mA	Total normal output
"L" level total average output current	Σ lolav		40	mA	Total normal output*4
"H" level maximum outputcurrent	Іон	_	-15	mA	Normal output*2
"H" level average outputcurrent	Іонач	_	-4	mA	Normal output*3
"H" level total maximum output current		_	-50	mA	Total normal output
"H" level maximum outputcurrent	ΣІон		-10	mA	Total output of P31 to P37, CLK1, CLK2, USBP.
		_	-20	mA	Total normal output*4
"H" level average total output currnt	ΣΙομαν	_	-10	mA	Total output of P31 to P37, CLK1, CLK2 and USBP.*4
Power consumption	Po		300	mW	
Operating temperature	Та	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	

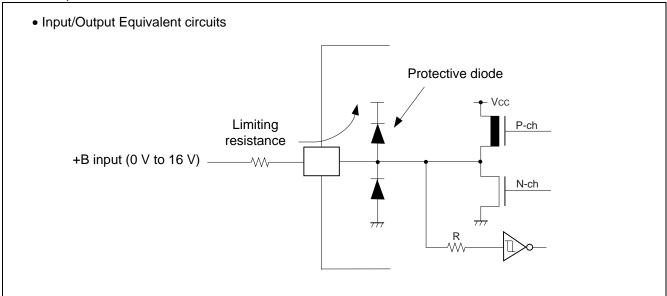
WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

^{*1:} V_I should not exceed the specified ratings. However, if the maximum current to /from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

^{*2:} Maximum output current is defined as the peak value at one curresponding pin.

^{*3 :} Average output current is defined as the average current flowing through one corresponding pin in an internal of 100 ms. (Average value : operating current × operating duty)

- *4: Average total output current is defined as the average current flowing through all corresponding pins in an internal of 100 ms.
- *5: Applicable to pins: P00 to P07, P10 to P17, P20 to P27, P40 to P45
 - Use within recommended operating conditions.
 - Use at DC voltage (current)
 - The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potentional may pass through the protective diode and increase the potentional at the Vcc pin, and this may affect other devices.
 - Note that if a +B signal is input when the microcontroller current is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on result.
 - Care must be taken not to leave the +B input pin open.
 - Note that analog system input pins other than the A/D input pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signl input.
 - Sample recommended circuits :



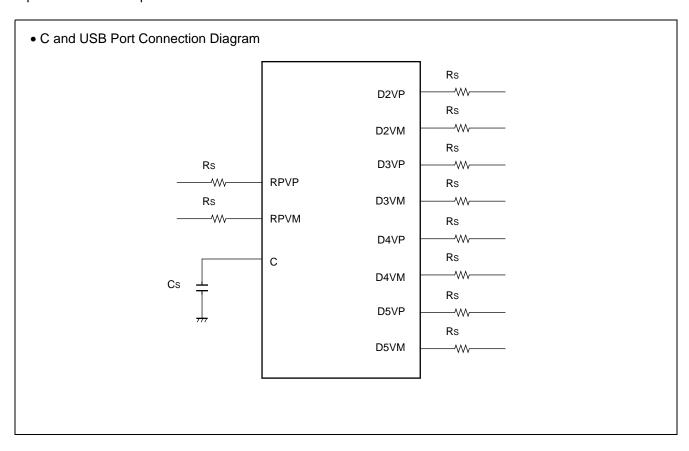
WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

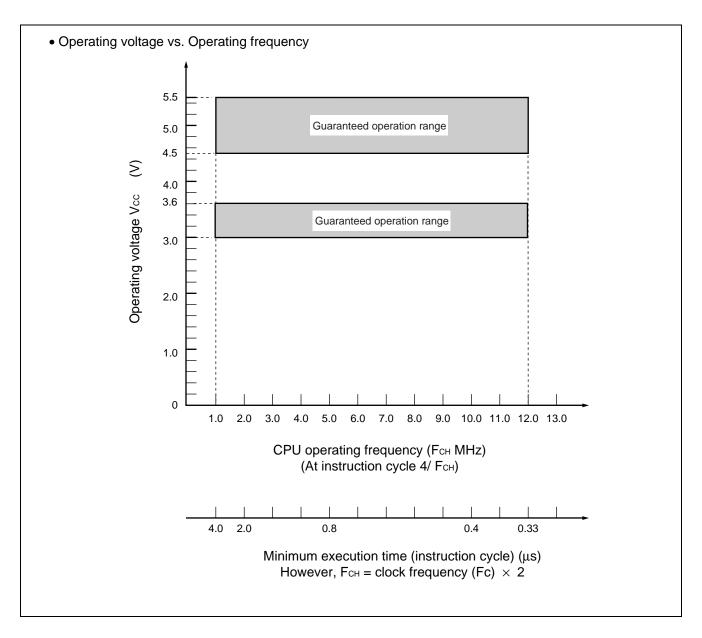
2. Recommended Operating Conditions

(Vss = 0 V)

Parameter	Symbol		Value		Unit	Remarks
Parameter	Symbol	Min	Тур	Max	Onit	Kelliaiks
Power supply voltage	Vcc	4.5	_	5.5	V	At Vcc = 5.0 V
Fower supply voltage	Vcc	3.0	_	3.6	V	At Vcc = 3.3 V*
Operating temperature	TA	-40	_	+85	°C	When the USB function is not in use.
Operating temperature	IA	0	_	+70	°C	When the USB function is in use
Smoothing capacitor	Cs	0.1	_	1.0	μF	At Vcc = 5.0 V*
Series resistance	Rs	_	16	_	Ω	When the USB function is in use

^{*:} Use either a ceramic capacitor or a capacitor with similar frequency characteristics. The capacity of the smoothing capacitor for the Vcc pin should be greater than that of the Cs. When using with a supply voltage of 3.3 V, connect pin C with Vcc to input 3.3 V.





WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

3. DC Characteristics (Power supply votage : 5.0 V)

(Vcc = 5.0 V, Vss = 0 V, $T_A = -40$ °C to +85 °C)

Barramastar	Sym	D:	Complition		Value		11:4	Domento
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level	Vін	P00 to P07, P10 to P17, P20 to P27, P40 to P47, P53, P54, MOD0, MOD1, MOD2		0.7 Vcc	_	Vcc+0.3	V	
Input voltage		P31 to P37	_	2.5		3.3	V	3 V
	RST, UCK, UI	_	0.8 Vcc	_	Vcc+0.3	V		
	Vihs	INT1 to INT7, SCK1, SCK2, SI1, SI2	_	2.9	_	3.3	V	3 V
	VIHI2C	SCL, SDA	_	0.8 Vcc	_	Vcc+5.5	V	
VII	VıL	P00 to P07, P10 to P17, P20 to P27, P40 to P47, P53, P54, MOD0, MOD1, MOD2	_	Vss-0.3		0.3 Vcc	V	
"L" level Input voltage		P31 to P37	_	Vss-0.3	_	0.9		3 V
	Vils	RST, INT1 to INT7, UCK, UI	_	Vss-0.3	_	0.2 Vcc	V	
	VILS	INT1 to INT7, SCK1, SCK2, SI1, SI2	_	Vss-0.3	_	0.6		3 V
	V _{ILI2C}	SCL, SDA		Vss-0.3		0.3 Vcc	٧	
Open-drain out- put application voltage	V _{D1}	P53, P54	_	Vss-0.3	_	Vcc+0.3	٧	
"H" level	Vон	P00 to P07, P10 to P17, P20 to P24, P40 to P47	lон = −2.0 mA	4.0		_	V	
Output voltage		P31 to P37, CLK1, CLK2	Iон = −1.0 mA	2.6	_	3.6 V	٧	3 V
		USBP	$I_{OH} = -2.4 \text{ mA}$	3.0		3.6 V	V	USB Pull up

(Continued)

(Vcc = 5.0 V, Vss = 0 V, TA = -40 °C to +85 °C)

Davamatar	Sym	Pin	Candition	`	Value			Remarks
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"L" level Output voltage	Vol	P00 to P07, P10 to P17, P20 to P24, P40 to P47, P53, P54, RST	IoL = 4.0 mA	_	_	0.4	V	
		P31 to P37, CLK1, CLK2	lo _L = 1.0 mA			0.4	V	3 V
Input leakage current (Hi-Z output	lu	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47,	0.0 V < V _I < V _{CC}	-5	_	+ 5	μА	When no pullup re sistance is speci fied
leakage current)		CLK1, CLK2		-5	_	+ 5	μΑ	
		USBP		- 5	_	+ 5	μΑ	
Open-drain out- put leakage cur- rent	ILIOD	P53, P54	0.0 V < V _I < V _{SS} + 5.5 V	_	_	+ 5	μА	
Pullup resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, RST	Vı = 0.0 V	25	50	100	kΩ	RST is excluded when pullup resistance available is specified.
			F _{CH} = 12.0 MHz,	_	29	42	mA	MB89F051
Dawar accept	Icc		$\begin{aligned} \text{Vcc} &= 5.0 \text{ V,} \\ t_{\text{inst}} &= 0.333 \mu\text{s} \end{aligned}$	_	28	41	mA	MB89051
current	ower supply rrent Iccs1 Vcc		$\begin{aligned} F_{CH} &= 12.0 \text{ MHz}, \\ V_{CC} &= 5.0 \text{ V}, \\ t_{inst} &= 0.333 \mu s \end{aligned}$	_	20	30	mA	Sleep mode
	Іссн		T _A = +25 °C		40	70	μΑ	Stop
Input capacitance	Cin	Other than Vcc, Vss and C	f = 1 MHz	_	5	15	pF	

4. DC Characteristics (Power supply votage: 3.3 V)

(Vcc = 3.3 V, Vss = 0 V, $T_A = -40$ °C to +85 °C)

Donomotor	Sym	D:-	Candition		Value		l lm !4	Domestre
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level Input voltage		P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, MOD0, MOD1, MOD2	1	0.7 Vcc	1	Vcc+0.3	V	
	Vihs	RST, UCK, UI, INT1 to INT7, SCK1, SCK2, SI1, SI2	1	0.8 Vcc	I	Vcc+0.3	٧	
	V _{IHI2C}	SCL, SDA	_	0.8 Vcc	_	Vcc+5.5	V	
"L" level Input voltage	VIL	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, MOD0, MOD1, MOD2	_	Vss-0.3	—	0.3 Vcc	V	
	VILS	RST, INT1 to INT7, UCK, UI, INT1 to INT7, SCK1, SCK2, SI1, SI2	_	Vss-0.3	_	0.2 Vcc	V	
	V _{ILI2C}	SCL, SDA	_	Vss-0.3		0.3 Vcc	V	
Open-drain output application voltage	V _{D1}	P53, P54	_	Vss-0.3	_	Vcc+0.3	V	
#112 Javal		P00 to P07, P10 to P17, P20 to P24, P40 to P47	Iон = −2.0 mA	2.6	—	_	٧	
"H" level Output voltage	Vон	P31 to P37, CLK1, CLK2	Iон = -1.0 mA	2.6		_	V	
		USBP	Iон = -2.4 mA	3.0	_	_	V	USB Pull up, Vcc = 3.1 V to 3.6 V

(Continued)

(Vcc = 3.3 V, Vss = 0 V, $T_A = -40$ °C to +85 °C)

Davamatar	Sym	Pin	Condition	`	Value			Pararka
Parameter	bol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"L" level Output voltage	Vol	P00 to P07, P10 to P17, P20 to P24, P40 to P47, P53, P54, RST	IoL = 4.0 mA	_	_	0.4	V	
		P31 to P37, CLK1, CLK2	IoL = 1.0 mA		_	0.4	V	
Input leakage current (Hi-Z output	lu	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47,	0.0 V < V _I < V _{CC}	-5		+5	μА	When no pullup resistance is specified
leakage current)		CLK1, CLK2		-5		+5	μΑ	
		USBP		-5	_	+5	μΑ	
Open-drain output leakage current	ILIOD	P53, P54	0.0 V < V ₁ < V ₅₅ +5.5 V	_		+5	μА	
Pullup resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P31 to P37, P40 to P47, P53, P54, RST	Vı = 0.0 V	25	50	100	kΩ	RST is excluded when pullup resistance available is specified.
			F _{CH} = 12.0 MHz,		29	42	mA	MB89F051
Dawar accept	Icc		$\begin{aligned} \text{Vcc} &= 3.3 \text{ V,} \\ t_{\text{inst}} &= 0.333 \mu\text{s} \end{aligned}$		28	41	mA	MB89051
Power supply current	Iccs ₁	Vcc	$\begin{aligned} F_{\text{CH}} &= 12.0 \text{ MHz}, \\ V_{\text{CC}} &= 3.3 \text{ V}, \\ t_{\text{inst}} &= 0.333 \mu s \end{aligned}$	_	20	30	mA	Sleep mode
	Іссн		T _A = +25 °C		40	70	μΑ	Stop
Input capacitance	Cin	Other than Vcc and Vss	f = 1 MHz		10		pF	

5. AC Characteristics

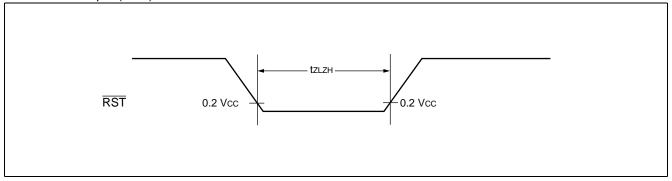
(1) Reset Timing

$$(Vcc = 5.0 \text{ V}, Vss = 0 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

Parameter	Svmbol	Condition	Value		Unit	Remarks
Parameter	Symbol	Condition	Min	Max		iverrial ks
RST "L" pulse width	t zlzh	_	48 theyl	_	ns	

Notes : • t_{HCYL} is the oscillation cycle for the internal main clock.

• If the reset pulse applied to the external reset pin (RST) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (RST).



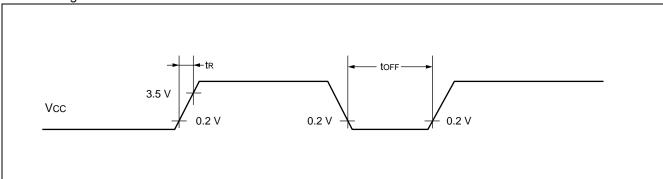
(2) Power-on reset

$$(Vss = 0 V, T_A = -40 \, ^{\circ}C to +85 \, ^{\circ}C)$$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
	Зуньон	Condition	Min	Max	Onit	Remarks
Power supply rising time	t R	_	0.066	50	ms	
Power supply cutoff time	toff	_	4	_	ns	Due to repeated operations

Note: The power supply must be up within the selected oscillation stabilization time.

When the supply voltage needs to be varied while operating, it is recommended to smoothly start up the voltage.

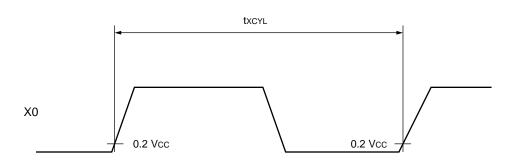


(3) Clock Timing

$$(Vss = 0 V, T_A = -40 \, ^{\circ}C to +85 \, ^{\circ}C)$$

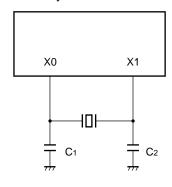
Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
1 drameter Syl	Symbol	Fili Ilaille	Condition	Min	Тур	Max	Oilit	
Clock frequency	Fc	X0, X1		_	6	_	MHz	
Clock cycle time	txcyL	X0, X1			166.6	_	ns	
Internal main clock frequency	Fсн	_	_	_	12	_	MHz	Twice the Fc
Internal clock cycle	thcyL	_		_	83.3	_	ns	txcyL/2

• X0 and X1 Timing and Conditions



• Clock Conditions

When a crystal resonator is used



(4) Instruction Cycle

(Vss = 0 V,
$$T_A = -40$$
 °C to +85 °C)

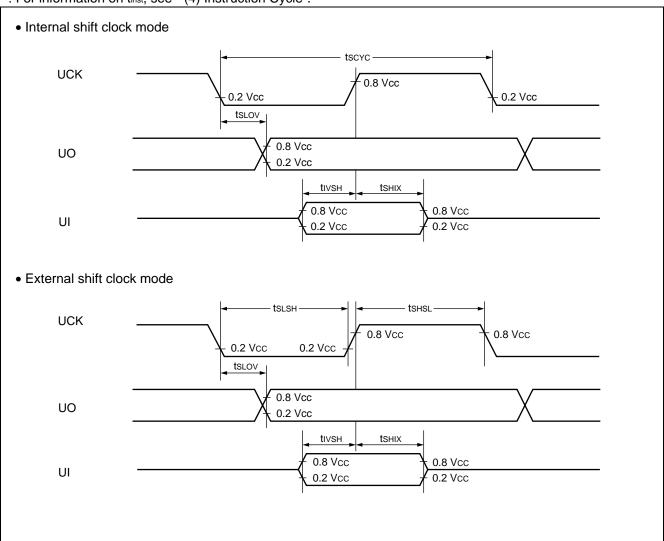
Parameter	Symbol	Value	Unit	Remarks
Instruction cycle (Min execution time)	t inst	4 / Fсн, 8 / Fсн, 16 / Fсн, 64 / Fсн	μs	When operating at FcH = 12 MHz tinst = 0.33 μs (4 / FcH)

(5) UART Serial I/O Timing

$$(Vcc = 5.0 \text{ V}, Vss = 0 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks
Farameter	Syllibol	riii iiaiiie	Condition	Min	Max	Oilit	Kemarks
Serial clock cycle time	tscyc	UCK		2 tinst*	_	μs	
$UCK \downarrow \to UO$	t sLov	UCK, UO	Internal shift clock mode	-200	+200	ns	
Valid UI → UCK ↑	tıvsн	UI, UCK		200	_	ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	t shix	UCK, UI		200	_	ns	
Serial clock "H" pulse width	t shsl	UCK		1 tinst*	_	μs	
Serial clock "L" pulse width	t slsh	UCK	External	1 tinst*	_	μs	
$UCK \downarrow \to UO$ time	t sLov	UCK, UO	shift clock	0	200	ns	
Valid UI → UCK ↑	tıvsн	UI, UCK	mode	200	_	ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	t shix	UCK, UI		200	_	ns	

*: For information on tinst, see "(4) Instruction Cycle".

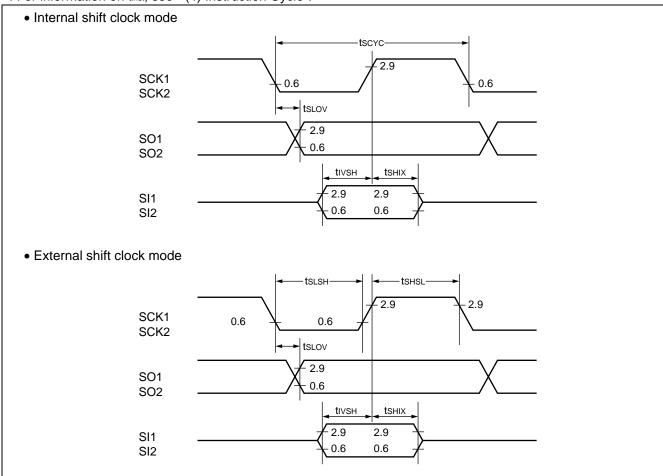


(6) Serial I/O Timing

 $(Vcc = 5.0 \text{ V}, Vss = 0V, T_A = -40 \, ^{\circ}\text{C to } +85 \, ^{\circ}\text{C})$

Daramatar	Cumbal	Pin name	Condition	Va	lue	Linit	Remarks
Parameter	Symbol	Fili lialile	Condition	Min	Max	Unit	Remarks
Serial clock cycle time	tscyc	SCK1, SCK2		2 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK1, SO1, SCK2, SO2	Internal shift clock mode	-200	+200	ns	
Valid SI → SCK ↑	t ıvsh	SCK1, SI1, SCK2, SI2		200	_	ns	
SCK $\uparrow \rightarrow$ Valid SI hold time	t shix	SCK1, SI1, SCK2, SI2		200	_	ns	
Serial clock "H" pulse width	t shsl	SCK1, SCK2		tinst*	_	μs	
Serial clock "L" pulse width	t slsh	SCK1, SCK2		tinst*	_	μs	
$SCK \downarrow \to SO$ time	tsLOV	SCK1, SO1, SCK2, SO2	External shift clock	0	200	ns	
Valid SI → SCK	t ıvsh	SCK1, SI1, SCK2, SI2	mode	200	_	μs	
$SCK \uparrow \rightarrow Valid SI hold time$	t sнıx	SCK1, SI1, SCK2, SI2		200	_	μs	

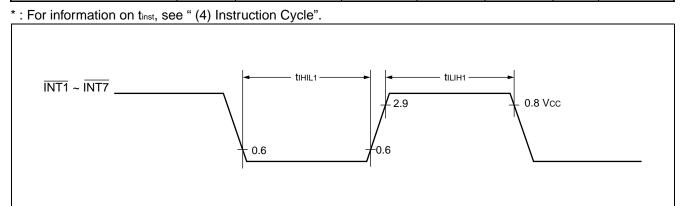
*: For information on tinst, see "(4) Instruction Cycle".



(7) Peripheral Input Timing

 $(Vcc = 5.0 \text{ V}, Vss = 0 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min	Max	Offic	ixemarks
Peripheral input "H" pulse width 1	t ıLıH1	INT1 to INT7	_	2 tinst*	_	μs	
Peripheral input "L" pulse width 1	t _{IHIL1}	INTT TO INTT	_	2 tinst*	_	μs	



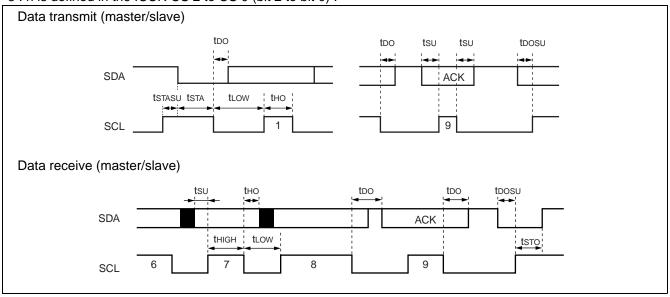
(8) I²C Timing

$$(Vcc = 5.0 \text{ V}, Vss = 0 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

Parameter	Sym bol	Pin	Val	11	Damarla	
Parameter			Min	Max	Unit	Remarks
Start condition output	t sta	SCL, SDA	$\begin{array}{l} 1 \ / \ 4 \times t_{inst}^{*1} \times \\ m_t^* \times n_t^{*3} - 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \times t_{\text{inst}}^{*1} \times \\ m_{t}^{*2} \times n_{t}^{*3} + 20 \end{array}$	ns	Master mode
Stop condition output	t sto	SCL, SDA	$1 / 4 \times t_{inst}^{*1} \times (m_t^{*2} \times n_t^{*3} + 8) - 20$	$1/4 \times t_{inst}^{*1} \times (m_t^{*2} \times n_t^{*3} + 8) + 20$	ns	Master mode
Start condition detect	t sta	SCL, SDA	$1 \ / \ 4 \times t_{\text{inst}}^{\star 1} \times 6 + 40$	_	ns	
Stop condition detect	t sto	SCL, SDA	$1 \ / \ 4 \times t_{\text{inst}}^{\star 1} \times 6 + 40$	_	ns	
Restart condition output	t stasu	SCL, SDA	$1 / 4 \times t_{inst}^{*1} \times (m_t^{*2} \times n_t^{*3} + 8) - 20$		ns	Master mode
Restart condition detect	t stasu	SCL, SDA	$1 \ / \ 4 \times t_{\text{inst}}^{\star 1} \times 4 + 40$	_	ns	
SCL output Low width	t LOW	SCL	$\begin{array}{c} 1 \ / \ 4 \times t_{\text{inst}}^{\star 1} \times m_{t}^{\star 2} \times n_{t}^{\star 3} \\ - \ 20 \end{array}$	$\begin{array}{c} 1 \ / \ 4 \times t_{inst}^{*1} \times m_t^{*2} \times n_t^{*3} \\ + \ 20 \end{array}$	ns	Master mode
SCL output High width	t HIGH	SCL	$\frac{1 / 4 \times t_{inst}^{*1} \times}{(m_t^{*2} \times n_t^{*3} + 8) - 20}$	$\frac{1/4 \times t_{inst}^{*1} \times}{(m_t^{*2} \times n_t^{*3} + 8) + 20}$	ns	Master mode
SDA output delay	t₀o	SDA	$1 \ / \ 4 \times t_{\text{inst}}^{*1} \times 4 - 20$	$1 / 4 \times t_{inst}^{*1} \times 4 + 20$	ns	
SDA output setup time after interrupt	toosu	SDA	$1 \mathrel{/} 4 \times t_{inst}^{\star 1} \times 4 - 20$	_	ns	
SCL input Low pulse width	t Low	SCL	$1 \ / \ 4 \times t_{\text{inst}}{}^{\star 1} \times 6 + 40$	_	ns	
SCL input High pulse width	t HIGH	SCL	$1 \ / \ 4 \times t_{inst}^{\star 1} \times 2 + 40$	_	ns	
SDA input setup time	t su	SDA	40	_	ns	
SDA hold time	t но	SDA	0	_	ns	

^{*1 :} For information on t_{inst}, see " (4) Instruction Cycle".

 $^{^{*}3}$: n is defined in the ICCR CS 2 to CS 0 (bit 2 to bit 0) .



^{*2:} m is defined in the ICCR CS 4 to CS 3 (bit 4 to bit 3).

6. FLASH Program/Erase characteristics

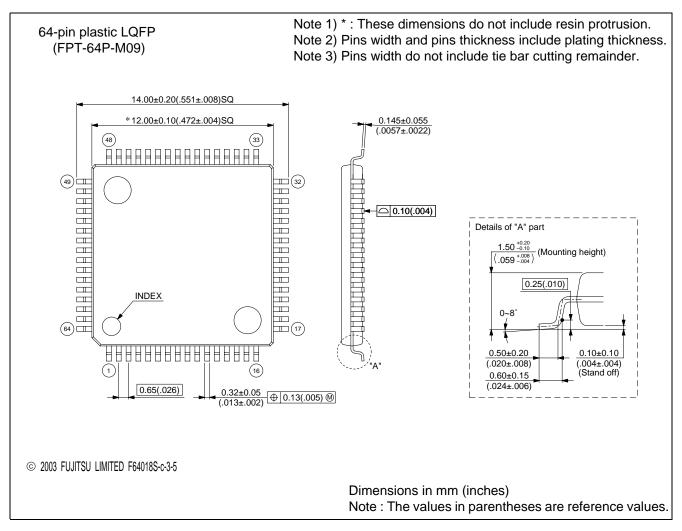
• Program/Erase characteristics

Parameter	Condition	Value			Unit	Remarks
		Min	Тур	Max	Onit	Remarks
Sector erase time		_	1	15	s	Except for the write time before internal erase operation
Chip erase time	$T_A = +25 ^{\circ}C$ Vcc = 5.0 V	_	5	75	s	Except for the write time before internal erase operation
Byte program time			8	3,600	μs	Except for the over head time of the system.
Prgram/erase cycle		10,000	_		cycle	

■ ORDERING INFORMATION

Part Number	Package	Remarks
MB89051PFM MB89F051PFM	64-pin plastic LQFP (FPT-64P-M09)	

■ PACKAGE DIMENSIONS



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